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Patent Plaque**JP5098372A2: AGE HARDENING SPECIAL COPPER ALLOY**[View Images \(1 pages\)](#) | [View INPADOC only](#)Country: **JP Japan**

Kind:

Inventor(s): **MIKAWA TSUNEAKI**Applicant(s): **MIKAWA TSUNEAKI
OKUHARA MASAHIKO**
[News, Profiles, Stocks and More about this company](#)Issued/Filed Dates: **April 20, 1993 / Oct. 8, 1991**Application Number: **JP1991000287279**IPC Class: **C22C 9/00;**

Abstract:

Purpose: To provide a copper alloy for electronic parts improved in mechanical properties.**Constitution:** The copper alloy can be obtained by incorporating, by weight, 0.1-5% nickel, 0.01-7% silicon, 0.01-10% iron, 0.01-7% titanium, and 0.001-1% boron into copper as a principal component. As compared with the conventional alloy, this age hardening special copper alloy is improved in electric conductivity, thermal conductivity, and mechanical properties, particularly hardness and elasticity.**COPYRIGHT:** (C)1993,JPO&Japio

Family:

Patent	Issued	Filed	Title
US5215711	June 1, 1993	April 6, 1992	Age-hardening type special Cu alloy
JP5098372A2	April 20, 1993	Oct. 8, 1991	AGE HARDENING SPECIAL COPPER ALLOY
JP2904372B2	June 14, 1999	Oct. 8, 1991	

3 family members shown above

Other Abstract Info:

CHEMABS 119(10)101485T CAN119(10)101485T DERABS C93-188438

Foreign References:

(No patents reference this one)

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